

AMENDMENTS TO THE CLAIMS

Claims 1-30 (canceled).

Claim 31 (Currently amended) A single semiconductor package consisting of ~~an unsupported~~ a single layer linearly consisting of at least two solder mask portions formed at selected locations, and between and adjacent said solder mask portions is a die pad portion of said layer contiguous to each solder mask portion; and lead portions of said layer adjacent to and contiguous to said solder mask portions, said die pad portion has a chip adhering to the die pad surface; a plurality of conductive elements are electrically connecting the chip and the lead portion of the layer; and a molded resin supporting and covering the chip, conductive elements, solder mask portions, lead portion of the layer and die pad layer; with the proviso that except for support provided by said molded resin, no other support is provided for said chip adhered to the die pad surface, conductive elements connected to said chip and to said lead portion of the layer, solder mask portions, lead portion of the layer and die pad layer;

and with the further proviso that the solder mask portions, lead portion of the layer and the die pad layer have a coplanar bottom surface which is not in contact with said molded resin.

Claim 32 (Previously submitted) The semiconductor package of claim 31, wherein the solder mask is made from photosensitive and insulative materials selected from the group consisting of polyimide and ultraviolet-curable resins.

Claim 33 (Previously submitted) The semiconductor package of claim 32, wherein the lead layer and die pad layer are made of conductive materials selected from the group consisting of nickel and gold.

Claim 34 (Previously submitted) The semiconductor package of claim 32, wherein the solder mask is formed by performing photolithography process on a polyimide or ultraviolet-curable resin layer.

Claim 35 (Previously submitted) The semiconductor package of claim 31, wherein the lead layer and die pad layer are formed by plating.

Claim 36 (Previously submitted) The semiconductor package of claim 31, wherein the conductive elements are made of a material selected from the group consisting of gold, copper and aluminum.

Claim 37 (Previously submitted) The semiconductor package of claim 31, wherein the die pad layer is replaced by a solder mask.

Claim 38 (Currently amended) A single semiconductor package consisting essentially of ~~an unsupported~~ a single layer linearly consisting essentially of at least two solder mask portions formed at selected locations, and between and adjacent said solder mask portions is a die pad portion of said layer contiguous to each solder mask portion; and lead portions of said layer adjacent to and contiguous to said solder mask portions, said die pad portion has a chip adhering by a silver paste to the die pad surface; a plurality of conductive elements are electrically connecting the chip and the lead portion of the layer; and a molded resin supporting and covering the chip, conductive elements, solder mask portions, lead layer and die pad portion of the layer; with the proviso that except for support provided by said molded resin, no other support is provided for said chip adhered to the die pad surface, conductive elements connected to said chip and to said lead portion of the layer, solder mask portions, lead portion of the layer and die pad layer;

and with the further proviso that the solder mask portions, lead portion of the layer and the die pad layer have a coplanar bottom surface which is not in contact with said molded resin.

Claim 39 (Previously submitted) The semiconductor package of claim 38, wherein the solder mask is made from photosensitive and insulative materials selected from the group consisting of polyimide and ultraviolet-curable resins.

Claim 40 (Previously submitted) The semiconductor package of claim 38, wherein the lead layer and die pad layer are made of conductive materials selected from the group consisting of nickel and gold.

Claim 41 (Previously submitted) The semiconductor package of claim 38, wherein the solder mask is formed by performing photolithography process on a polyimide or ultraviolet-curable resin layer.

Claim 42 (Previously submitted) The semiconductor package of claim 38, wherein the lead layer and die pad layer are formed by plating.

Claim 43 (Previously submitted) The semiconductor package of claim 38, wherein the conductive elements are made of a material selected from the group consisting of gold, copper and aluminum.

Claim 44 (Previously submitted) The semiconductor package of claim 38, wherein the die pad layer is replaced by a solder mask.

Claims 45-46 (Cancelled)